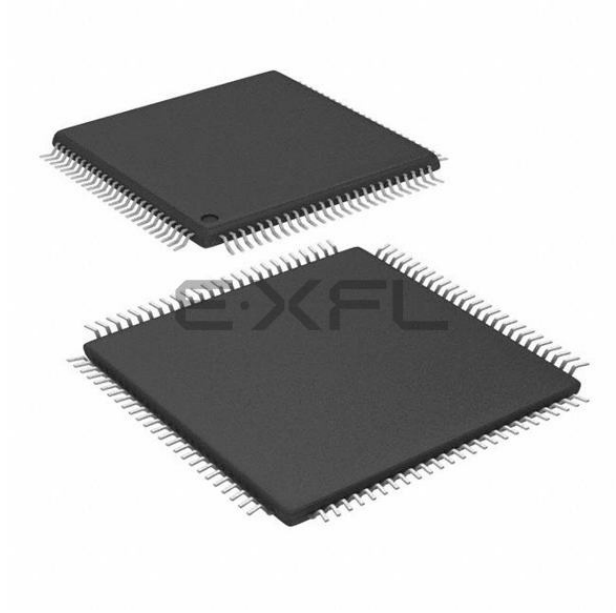
Microchip Technology - PIC24HJ128GP210AT-I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp210at-i-pt

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/C-0	R/W-0	U-0	U-0
—	—	—	—	IPL3(1)	PSV	—	—
bit 7							bit 0

Legend:	C = Clear only bit		
R = Readable bit	W = Writable bit	-n = Value at POR	‘1’ = Bit is set
0’ = Bit is cleared	‘x = Bit is unknown	U = Unimplemented bit, read as ‘0’	

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(1)
1 = CPU interrupt priority level is greater than 7
0 = CPU interrupt priority level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space visible in data space
0 = Program space not visible in data space

bit 1-0 **Unimplemented:** Read as ‘0’

Note 1: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

TABLE 4-6: TIMER REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (for 32-bit timer operations only)																xxxx
TMR3	010A	Timer3 Register																0000
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR4	0114	Timer4 Register																0000
TMR5HLD	0116	Timer5 Holding Register (for 32-bit operations only)																xxxx
TMR5	0118	Timer5 Register																0000
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR6	0122	Timer6 Register																0000
TMR7HLD	0124	Timer7 Holding Register (for 32-bit operations only)																xxxx
TMR7	0126	Timer7 Register																0000
PR6	0128	Period Register 6																FFFF
PR7	012A	Period Register 7																FFFF
T6CON	012C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T7CON	012E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR8	0130	Timer8 Register																0000
TMR9HLD	0132	Timer9 Holding Register (for 32-bit operations only)																xxxx
TMR9	0134	Timer9 Register																0000
PR8	0136	Period Register 8																FFFF
PR9	0138	Period Register 9																FFFF
T8CON	013A	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T9CON	013C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

TABLE 4-20: ECAN1 REGISTER MAP WHEN C1CTRL1.WIN = 1 FOR PIC24HJXXXGP506A/510A/610A DEVICES ONLY (CONTINUED)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1RXF1EID	0446	EID<15:8>								EID<7:0>								xxxx
C1RXF2SID	0448	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF2EID	044A	EID<15:8>								EID<7:0>								xxxx
C1RXF3SID	044C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF3EID	044E	EID<15:8>								EID<7:0>								xxxx
C1RXF4SID	0450	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF4EID	0452	EID<15:8>								EID<7:0>								xxxx
C1RXF5SID	0454	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF5EID	0456	EID<15:8>								EID<7:0>								xxxx
C1RXF6SID	0458	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF6EID	045A	EID<15:8>								EID<7:0>								xxxx
C1RXF7SID	045C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF7EID	045E	EID<15:8>								EID<7:0>								xxxx
C1RXF8SID	0460	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF8EID	0462	EID<15:8>								EID<7:0>								xxxx
C1RXF9SID	0464	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF9EID	0466	EID<15:8>								EID<7:0>								xxxx
C1RXF10SID	0468	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF10EID	046A	EID<15:8>								EID<7:0>								xxxx
C1RXF11SID	046C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF11EID	046E	EID<15:8>								EID<7:0>								xxxx
C1RXF12SID	0470	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF12EID	0472	EID<15:8>								EID<7:0>								xxxx
C1RXF13SID	0474	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF13EID	0476	EID<15:8>								EID<7:0>								xxxx
C1RXF14SID	0478	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF14EID	047A	EID<15:8>								EID<7:0>								xxxx
C1RXF15SID	047C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF15EID	047E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

REGISTER 7-18: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	DMA1IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP<2:0>			—	U1TXIP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **DMA1IP<2:0>:** DMA Channel 1 Data Transfer Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **AD1IP<2:0>:** ADC1 Conversion Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 9-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER(2)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN<5:0>(1)					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

111111 = Center frequency – 0.375% (7.345 MHz)
•
•
•
100001 = Center frequency – 11.625% (6.52 MHz)
100000 = Center frequency – 12% (6.49 MHz)
011111 = Center frequency + 11.625% (8.23 MHz)
011110 = Center frequency + 11.25% (8.20 MHz)
•
•
•
000001 = Center frequency + 0.375% (7.40 MHz)
000000 = Center frequency (7.37 MHz nominal)

Note 1: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation and is neither characterized nor tested.

2: This register is reset only on a Power-on Reset (POR).

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the PIC24HJXXXGPX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJXXXGPX06A/X08A/X10A devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. PIC24HJXXXGPX06A/X08A/X10A devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24HJXXXGPX06A/X08A/X10A devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24HJXXXGPX06A/X08A/X10A devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode has these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled
- The LPRC clock continues to run in Sleep mode if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation is disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV  #IDLE_MODE     ; Put the device into IDLE mode
```

11.2 Open-Drain Configuration

In addition to the PORT, LAT and TRIS registers for data control, some port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

11.3 Configuring Analog Port Pins

The use of the ADxPCFGH, ADxPCFGL and TRIS registers control the operation of the Analog-to-Digital port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) is converted.

Clearing any bit in the ADxPCFGH or ADxPCFGL register configures the corresponding bit to be an analog pin. This is also the Reset state of any I/O pin that has an analog (ANx) function associated with it.

Note:	In devices with two ADC modules, if the corresponding PCFG bit in either AD1PCFGH(L) and AD2PCFGH(L) is cleared, the pin is configured as an analog input.

When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

Note:	The voltage on an analog input pin can be between -0.3V to (VDD + 0.3 V).

11.4 I/O Port Write/Read Timing

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a NOP.

11.5 Input Change Notification

The input change notification function of the I/O ports allows the PIC24HJXXXGPX06A/X08A/X10A devices to generate interrupt requests to the processor in response to a change-of-state on selected input pins. This feature is capable of detecting input change-of-states even in Sleep mode, when the clocks are disabled. Depending on the device pin count, there are up to 24 external signals (CN0 through CN23) that can be selected (enabled) for generating an interrupt request on a change-of-state.

There are four control registers associated with the CN module. The CNEN1 and CNEN2 registers contain the CN interrupt enable (CNxIE) control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up connected to it. The pull-ups act as a current source that is connected to the pin and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the weak pull-up enable (CNxPUE) bits for each of the CN pins. Setting any of the control bits enables the weak pull-ups for the corresponding pins.

Note:	Pull-ups on change notification pins should always be disabled whenever the port pin is configured as a digital output.

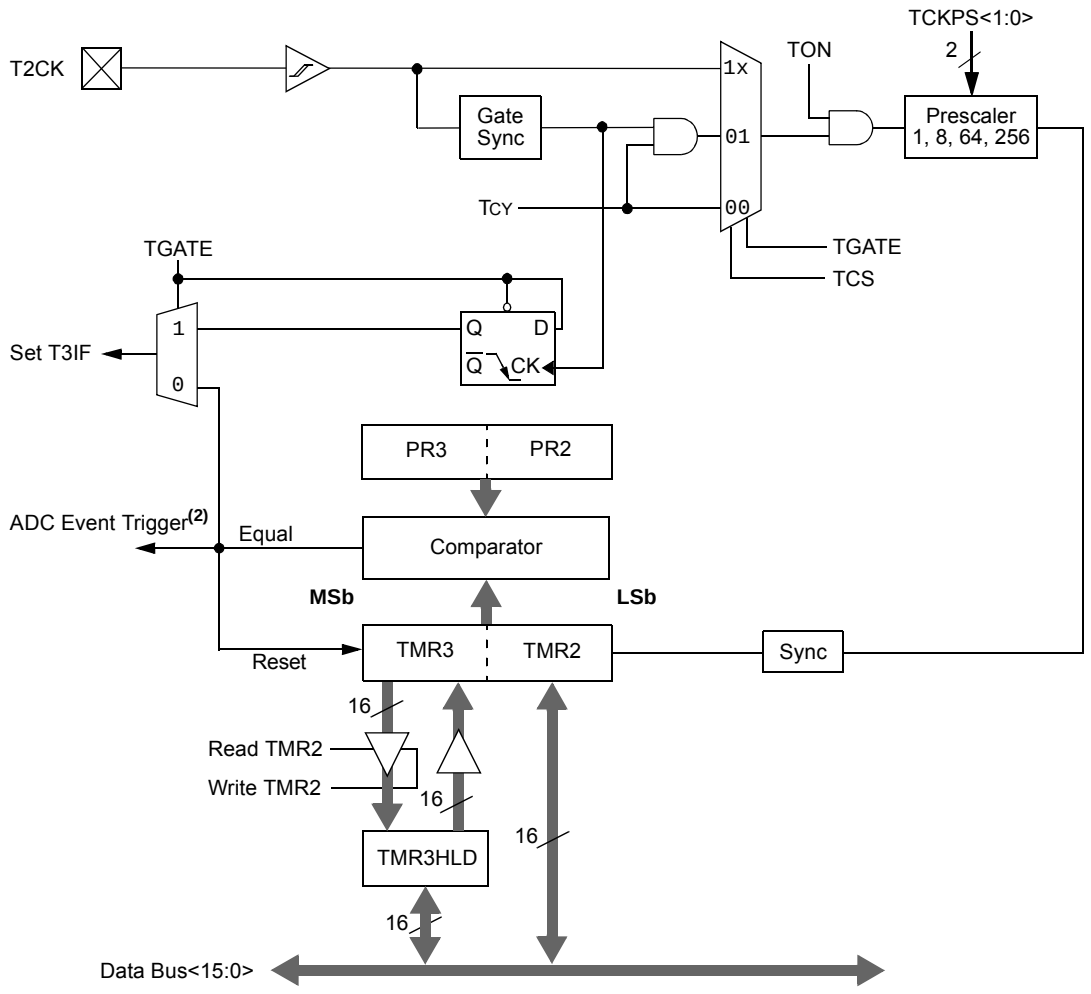
EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV     0xFF00, W0              ; Configure PORTB<15:8> as inputs
MOV     W0, TRISBB              ; and PORTB<7:0> as outputs
NOP                             ; Delay 1 cycle
btss    PORTB, #13              ; Next Instruction
```

A block diagram for a 32-bit timer pair (Timer4/5) example is shown in Figure 13-1 and a timer (Timer4) operating in 16-bit mode example is shown in Figure 13-2.

Note:	Only Timer2 and Timer3 can trigger a DMA data transfer.

FIGURE 13-1: TIMER2/3 (32-BIT) BLOCK DIAGRAM(1)



Note 1: The 32-bit timer control bit, T32, must be set for 32-bit timer/counter operation. All control bits are respective to the T2CON register.

2: The ADC event trigger is available only on Timer2/3.

NOTES:

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware set or clear when Start, Repeated Start or Stop detected.

bit 2 **R_W:** Read/Write Information bit (when operating as I^2C slave)
1 = Read – indicates data transfer is output from slave
0 = Write – indicates data transfer is input to slave
Hardware set or clear after reception of I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive complete, I2CxRCV is full
0 = Receive not complete, I2CxRCV is empty
Hardware set when I2CxRCV is written with received byte. Hardware clear when software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit complete, I2CxTRN is empty
Hardware set when software writes I2CxTRN. Hardware clear at completion of data transmission.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0 HC	R/W-0	R-0	R-1
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN(1)	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/C-0	R-0
URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware cleared		C = Clear only bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register, and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle state is '0'
- 0 = UxTX Idle state is '1'

If IREN = 1:
- 1 = IrDA® encoded UxTX Idle state is '1'
- 0 = IrDA® encoded UxTX Idle state is '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** Transmit Break bit
- 1 = Send Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission disabled or completed

bit 10 **UTXEN:** Transmit Enable bit(1)
- 1 = Transmit enabled, UxTX pin controlled by UARTx
- 0 = Transmit disabled, any pending transmission is aborted and buffer is reset. UxTX pin controlled by port.

bit 9 **UTXBF:** Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty, a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on UxRSR transfer making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on UxRSR transfer making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the UxRSR to the receive buffer. Receive buffer has one or more characters.

Note 1: Refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

TABLE 24-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 3 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -10 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -6 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -5 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -12 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -11 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -16 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -12 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -4 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

TABLE 24-35: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specificiation.

4: Assumes 50 pF load on all SPIx pins.

TABLE 24-43: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	76	—	—	ns	—
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	—
Conversion Rate							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	—
AD57	TSAMP	Sample Time	2 TAD	—	—	—	—
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2.0 TAD	—	3.0 TAD	—	Auto-Convert Trigger not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2.0 TAD	—	3.0 TAD	—	—
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2)	—	0.5 TAD	—	—	—
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2,3)	—	—	20	μs	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because the sample caps eventually loses charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: tDPU is the time required for the ADC module to stabilize when it is turned on (AD1CON1<ADON> = 1). During this time, the ADC result is indeterminate.

TABLE 24-44: DMA READ/WRITE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
DM1a	DMA Read/Write Cycle Time	—	—	2 TCY	ns	This characteristic applies to PIC24HJ256GPX06A/X08A/X10A devices only.
DM1b	DMA Read/Write Cycle Time	—	—	1 TCY	ns	This characteristic applies to all devices with the exception of the PIC24HJ256GPX06A/X08A/X10A.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC61c	3	5	μA	+150°C	3.3V	Watchdog Timer Current: ΔIWDT(2,4)

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 25-5: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	**Typical(1)**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	39	45	1:2	mA	+150°C	3.3V	20 MIPS
HDC72f	18	25	1:64	mA			
HDC72g	18	25	1:128	mA			

Note 1: Parameters with Doze ratios of 1:2 and 1:64 are characterized, but are not tested in manufacturing.

TABLE 25-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

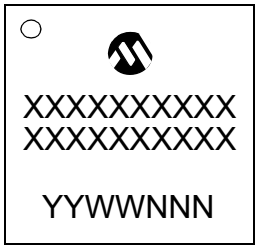
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

27.0 PACKAGING INFORMATION

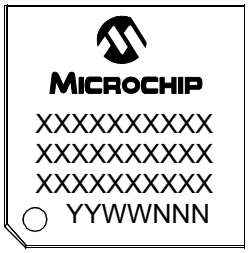
27.1 Package Marking Information

64-Lead QFN (9x9x0.9mm)

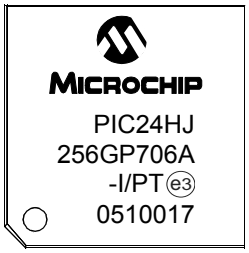


Example

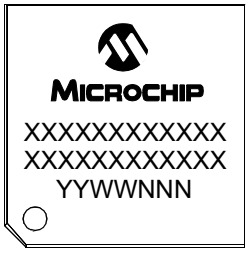
64-Lead TQFP (10x10x1 mm)



Example

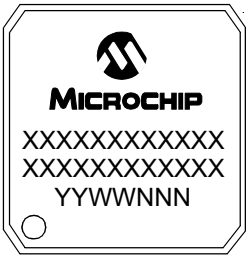


100-Lead TQFP (12x12x1 mm)



Example

100-Lead TQFP (14x14x1 mm)



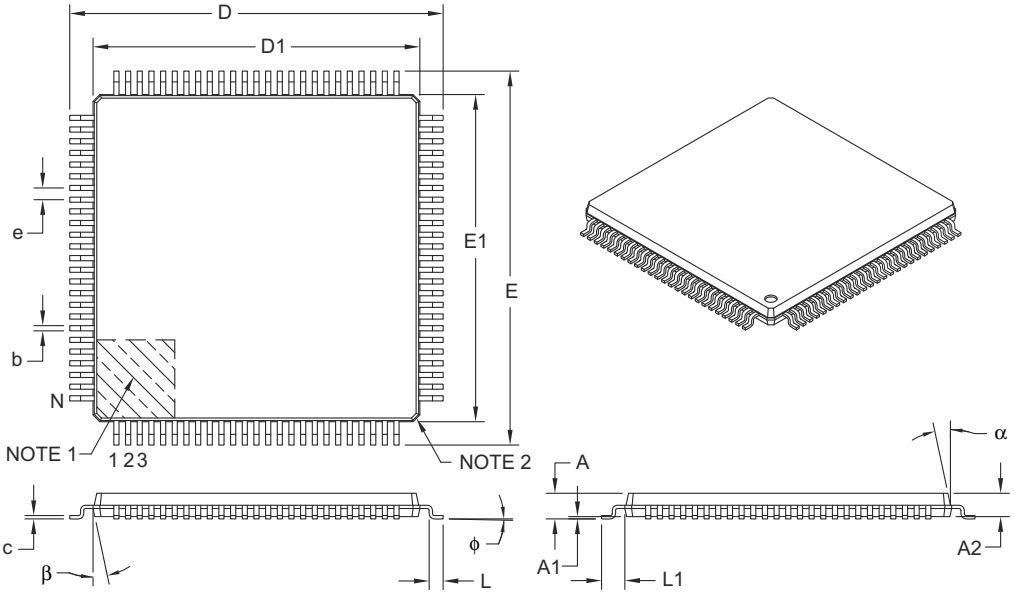
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

Revision D (June 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE B-3: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-Bit Microcontrollers"	Updated the Recommended Minimum Connection (see Figure 2-1).
Section 9.0 "Oscillator Configuration"	Updated the COSC<2:0> and NOSC<2:0> bit value definitions for '001' (see Register 9-1).
Section 20.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the Analog-to-Digital Conversion Clock Period Block Diagram (see Figure 20-2).
Section 21.0 "Special Features"	Added Note 3 to the On-chip Voltage Regulator Connections (see Figure 21-1).
Section 24.0 "Electrical Characteristics"	Updated **"Absolute Maximum Ratings"**. Updated Operating MIPS vs. Voltage (see Table 24-1). Removed parameter DC18 from the DC Temperature and Voltage Specifications (see Table 24-4). Updated the notes in the following tables: • Table 24-5 • Table 24-6 • Table 24-7 • Table 24-8 Updated the I/O Pin Output Specifications (see Table 24-10). Updated the Conditions for parameter BO10 (see Table 24-11). Updated the Conditions for parameters D136b, D137b, and D138b (T_A = 150ºC) (see Table 24-12).
Section 25.0 "High Temperature Electrical Characteristics"	Updated **"Absolute Maximum Ratings"**. Updated the I/O Pin Output Specifications (see Table 25-6). Removed Table 25-7: DC Characteristics: Program Memory.

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